Connector for Memory Stick Micro™

SCNA Series



Minimum mounting area for compact devices.

For SD Memory Card

For microSD™

For SIM Card 8pins

For W-SIM



For Memory Stick™

Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module



Features

 Minimized mounting area prevents negation of size advantage of the card.

Applications

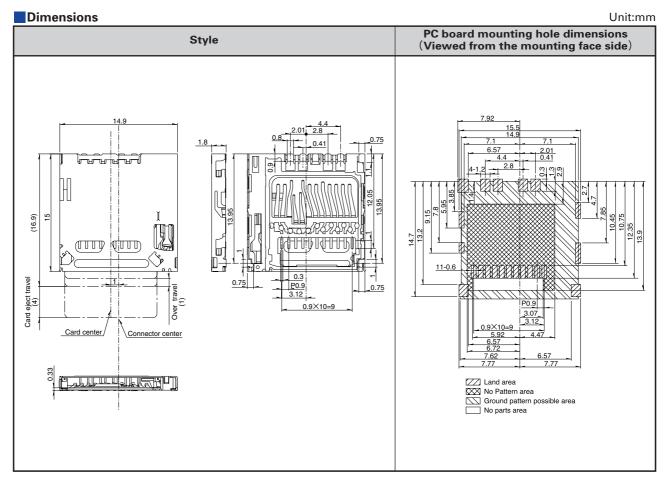
 For mobile phones, personal digital assistants, digital still cameras, compact audio equipment

Typical Specifications

Items		Specifications	
Structure	Applicable media	Memory Stick Micro™	
	Mounting type	Surface mounting type	
	Mounting style	Standard mount	
	Media ejection structure	Push-push type	
Performance	Operating temperature range	−25°C to +60°C	
	Voltage proof	250V AC 1minute	
	Insulation resistance (Initial)	1,000MΩ min.	
	Contact resistance (Initial)	40mΩ max.	
	Insertion and removal cycle	12,000cycles	

Product Line

Media ejection structure	Mounting system	Stand-off (mm)	Packing system	Product No.
Push-push type	Standard mount	0	Taping	SCNA1A0300



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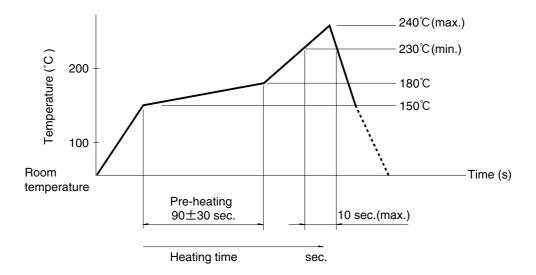
For Express Card™

For CMOS Camera Module

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
- 3. Temperature profile (Surface of products).



Combine Type

SD Memory Card

microSD™ Card

SIM Card 8pins

For

For W-SIM

Memory Stick Micro™

Memory

Stick™

For Compact Flash™

For PC cards supporting CardBus

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For CMOS Camera Module

Cautions for using this product

- 1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
- 2. Avoid use of water-soluble soldering flux, since it may corrode the product.
- 3. Check and conform to reflow soldering requirements under actual mass production conditions.
- 4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
- 5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.